

QIAOXIN N-Channel **SuperTrench II** Power MOSFET

Description

The NCEP072N10A uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(on)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

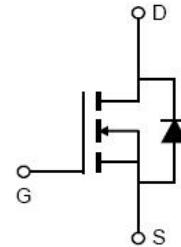
General Features

- $V_{DS} = 100V, I_D = 88A$
- $R_{DS(on)} = 6.2m\Omega$ (typical) @ $V_{GS} = 10V$
- $R_{DS(on)} = 8.4m\Omega$ (typical) @ $V_{GS} = 4.5V$
- Excellent gate charge $\times R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175°C operating temperature
- Pb-free lead plating

TO-220



Top View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VCRR 072N10A	VCRR072N10A	TO-220-3L	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	88	A
Drain Current-Continuous($T_c=100^\circ C$)	$I_D (100^\circ C)$	63	A
Pulsed Drain Current	I_{DM}	352	A
Maximum Power Dissipation	P_D	125	W
Derating factor		0.83	W/ $^\circ C$
Single pulse avalanche energy (Note 5)	E_{AS}	387	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	1.2	$^\circ C/W$
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.7	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=44\text{A}$	-	6.2	7.2	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=44\text{A}$		8.4	9.6	
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=44\text{A}$		60	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	4120	-	PF
Output Capacitance	C_{oss}		-	322	-	PF
Reverse Transfer Capacitance	C_{rss}		-	12.5	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=50\text{V}, I_{\text{D}}=44\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$	-	17	-	nS
Turn-on Rise Time	t_{r}		-	11	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	36	-	nS
Turn-Off Fall Time	t_{f}		-	9	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=44\text{A}, V_{\text{GS}}=10\text{V}$	-	81	-	nC
Gate-Source Charge	Q_{gs}		-	13.9	-	nC
Gate-Drain Charge	Q_{gd}		-	21.3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=44\text{A}$	-		1.2	V
Diode Forward Current (Note 2)	I_{s}		-	-	88	A
Reverse Recovery Time	t_{rr}	$T_{\text{J}} = 25^\circ\text{C}, I_{\text{F}} = 44\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ (Note 3)	-	62	-	nS
Reverse Recovery Charge	Q_{rr}		-	109	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_j=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

Typical Electrical and Thermal Characteristics

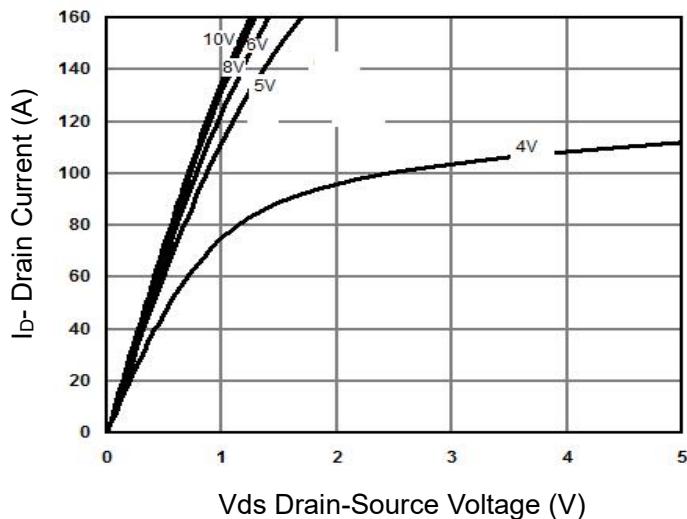


Figure 1 Output Characteristics

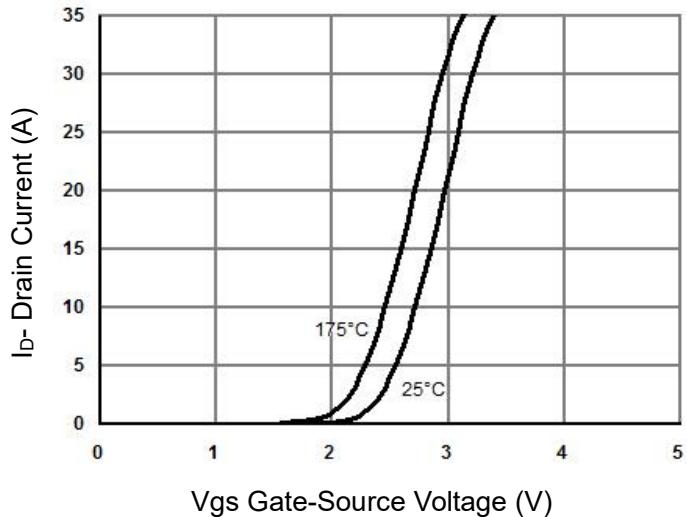


Figure 2 Transfer Characteristics

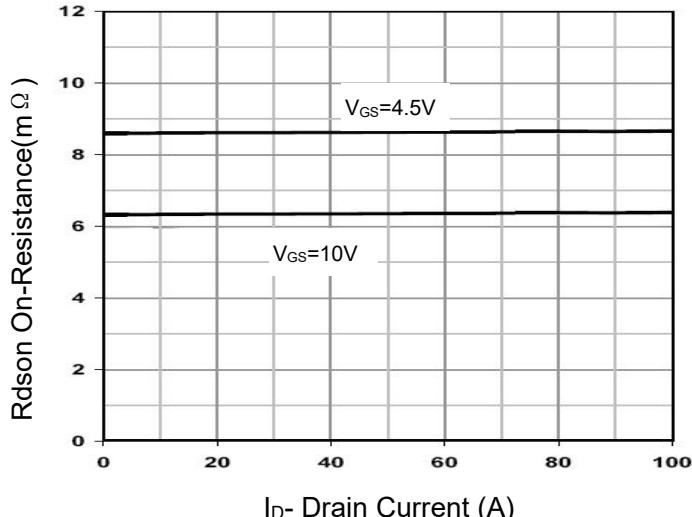


Figure 3 Rdson- Drain Current

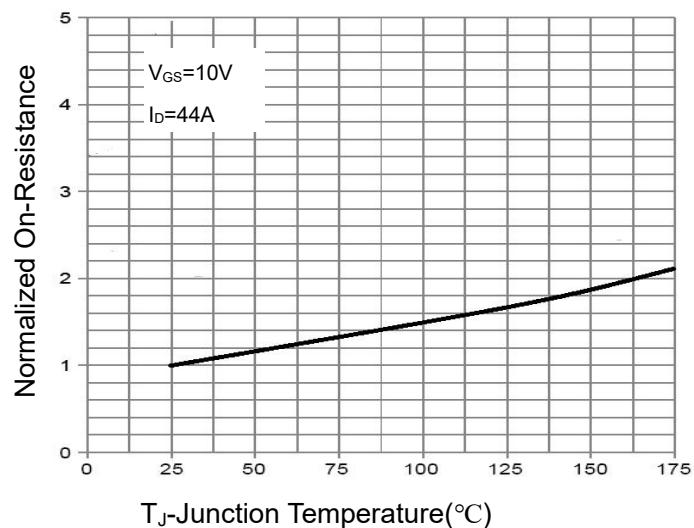


Figure 4 Rdson-Junction Temperature

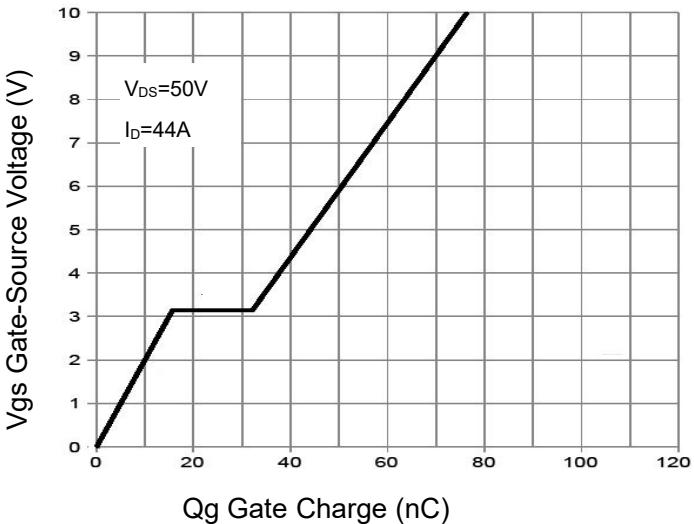


Figure 5 Gate Charge

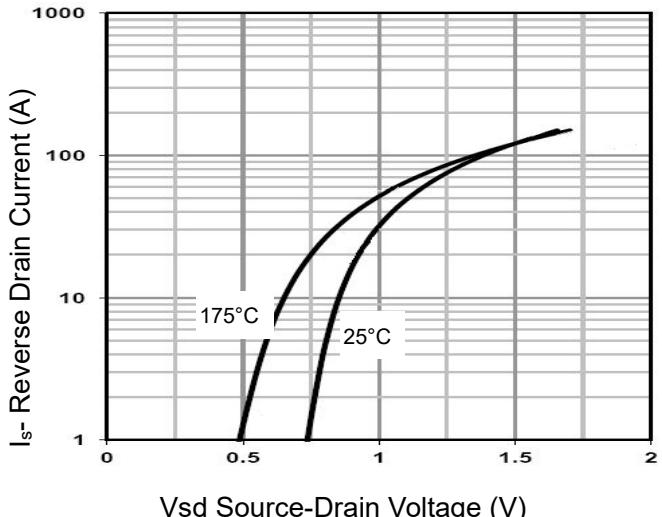


Figure 6 Source- Drain Diode Forward

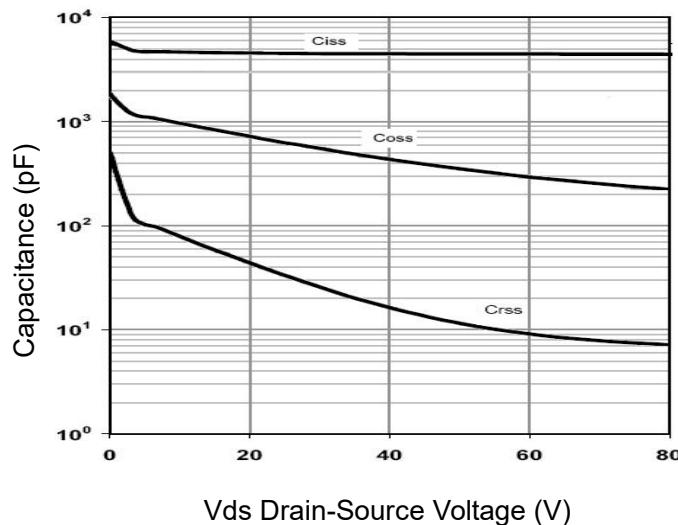


Figure 7 Capacitance vs Vds

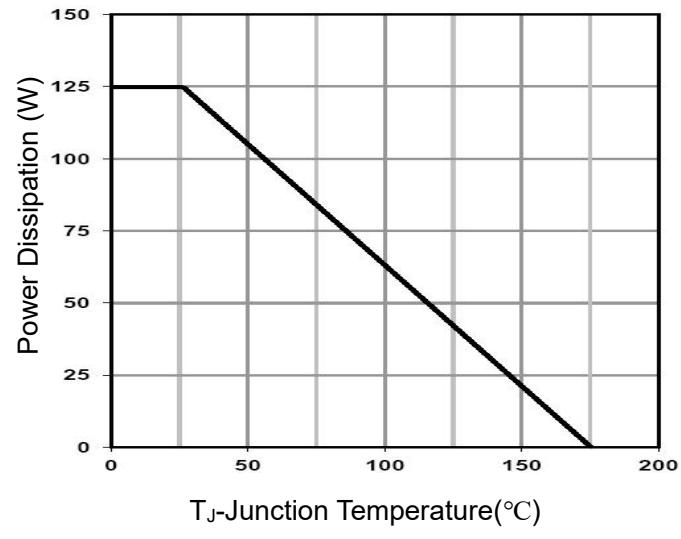


Figure 9 Power De-rating

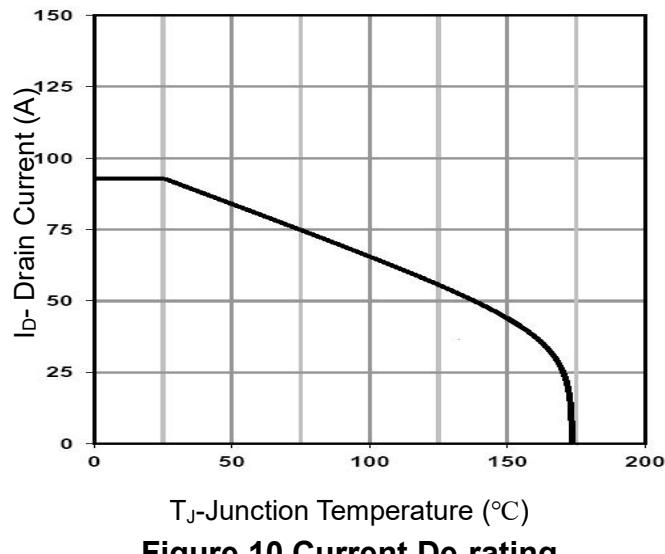


Figure 10 Current De-rating

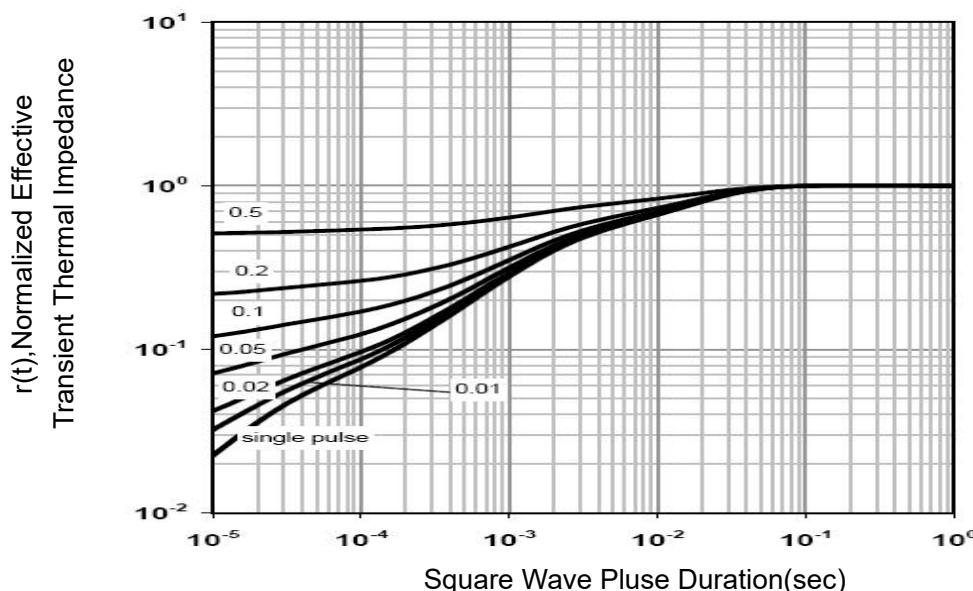
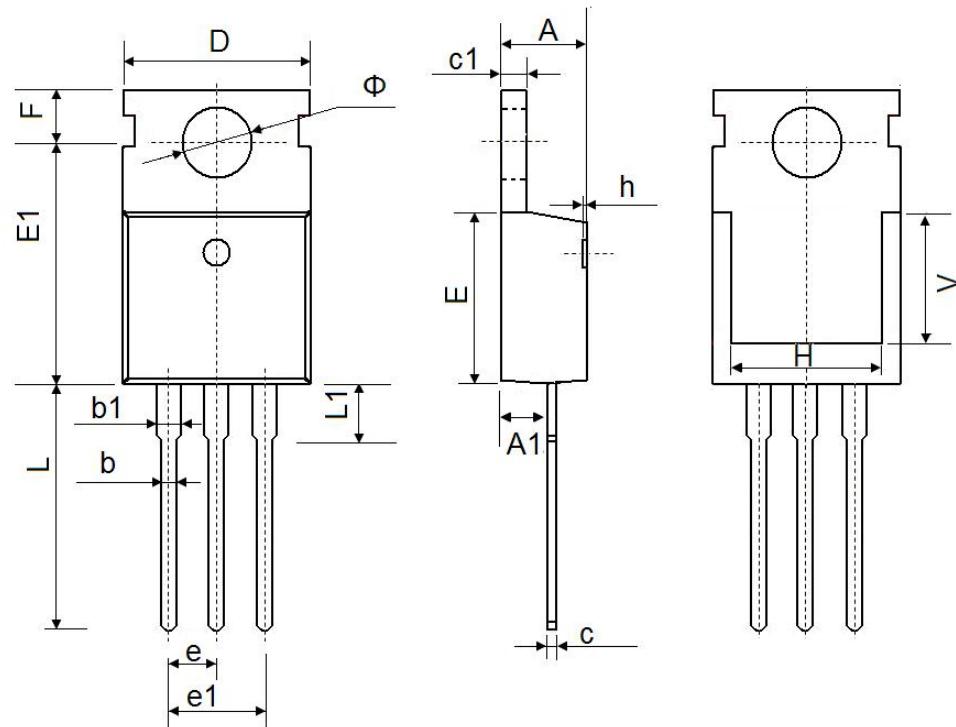


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150

Attention

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